



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



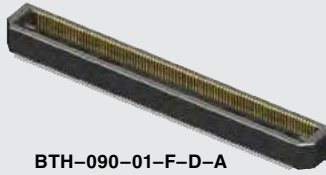
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BTH-090-01-F-D-A



BTH SERIES

(0.50 mm) .0197"

BASIC BLADE & BEAM HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BTH

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50 μ" (1.27 μm) Ni
Current Rating: 2.0 A per pin (1 pin powered per row)
Flammability Rating: UL 94 VO
Operating Temp Range: -55 °C to +125 °C
Voltage Rating: 275 VAC
Max Cycles: 100
RoHS Compliant: Yes

PROCESSING

Lead-Free Solderable: Yes
SMT Lead Coplanarity:
 Vertical= (0.10 mm) .004" max (030-090)
 Vertical= (0.15 mm) .006" max (120-150)
 Right-angle= (0.15 mm) .006" max (030-090)
Board Stacking:
 For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00) .197

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- 30 μ" (0.76 μm) Gold
 - Edge Mount Capability
 - 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BTH — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with: BSH

-030, -050, -060, -090, -120, -150

-F
= Gold Flash on contact, Matte Tin on tail

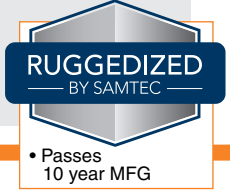
-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-C*
= Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails

-K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad

-TR
= Tape & Reel (120 positions maximum)

*Note: -C Plating passes 10 year MFG testing



BTH — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **RA** — **WT** — **OTHER OPTION**

Mates with: BSH

-030, -060, -090

-F
= Gold Flash on contact, Matte Tin on tail

-L
= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

-K
= (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad